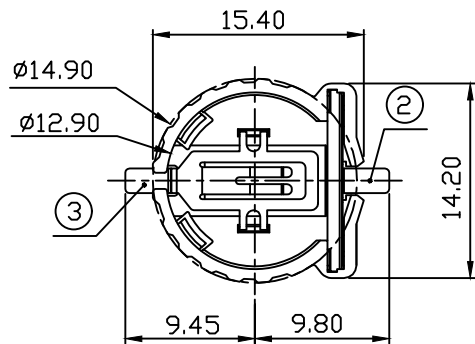
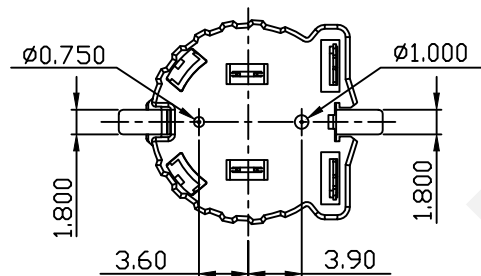


PCB Layout Diagram
Top View



1.MATERIAL:

a.HOUSING:PPA

b.CONTACT:PHOSPHOR BRONZE

(SURFACE PLATING:Au 1u")

2.ELECTRIC:

a.CONTACT RESISTANCE:30 MILLIOHMS MAX

b.INSULATION RESISTANCE:1000 MEA OHMS MIN

c.DIELECTNIC VOLTAGE:500V AC ONE SEC LEVEL

d.OPERATING TEMPERATURE:-25°C~+85°C

3	TERMINAL(-)	1	PHOSPHOR BRONZE,T=0.20mm	Gold Plating And Ni Under-Plating
2	TERMINAL(+)	1	PHOSPHOR BRONZE,T=0.20mm	Gold Plating and Ni Under-Plating
1	HOUSING	1	PPA	BROWN
NO.	PART NAME	Q'TY	MATERIAL	PLATING &COLOR

RHTECP NINGBO RHT ELECTRONIC CO.,LTD

UNITS:mm	SHEET SIZE: A4			SCALE:---
0~3	3~18	18~50	50~120	
±0.12	±0.15	±0.3	±0.5	

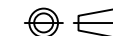
DRWN BY PAN

CHK'D BY FENG

APPR BY ZHAN

CR1220 COIN CELL BATTERY HOLDER SMT

THIRD ANGLE PROJECTION



RE-BH-CR1220-02